## **Application Data Sheet**

#### **Application Information**

Application Type:: Regular

Subject Matter:: Utility

Suggested Group Art Unit:: N/A

CD-ROM or CD-R?:: None

Sequence submission?:: None

Computer Readable Form (CRF)?:: No

Title:: METHOD OF FORMING METAL LINE OF

SEMICONDUCTOR DEVICE

Attorney Docket Number:: 29936/39847

Request for Early Publication?:: No

Request for Non-Publication?:: No

Total Drawing Sheets:: 6

Small Entity?:: No

Petition included?:: No

Secrecy Order in Parent Appl.?:: No

#### **Applicant Information**

Applicant Authority Type:: Inventor

Primary Citizenship Country:: Korea, Republic of

Status:: Full Capacity

Given Name:: Shin

Middle Name:: Seung

Family Name:: Park

City of Residence:: Kyungki-Do

Country of Residence:: Korea

Street of mailing address:: San 136-1, Ami-Ri, Bubal-Uep

Ichon-shi

City of mailing address:: Kyungki-Do

Country of mailing address:: Korea, Republic of

## **Correspondence Information**

Correspondence Customer Number::

04743

Representative Information

Representative Customer Number::

04743

### **Foreign Priority Information**

Country::	Application number::	FilingDate::	Priority Claimed::
Korea, Republic of	2003-21058	04/03/03	Yes

# **Assignee Information**

Assignee name::

HYNIX SEMICONDUCTOR INC.

Street of mailing address::

San 136-1, Ami-Ri, Bubal-Uep, Ichon-Shi

City of mailing address::

Kyungki-Do

Country of mailing address::

Korea, Republic of

Postal or Zip Code of mailing address::

467-860